



Material Content Data Sheet



Sales Product Name		BFP 181 E7764		Issued		20. July 2018			
MA#		MA000770690							
Package		PG-SOT143-4-1		Weight*		11.06 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.002	0.02		163		
	non noble metal	tin	7440-31-5	0.000	0.00		42		
	inorganic material	silicon	7440-21-3	0.013	0.12	0.14	1208	1413	
leadframe	non noble metal	nickel	7440-02-0	1.673	15.12		151177		
	non noble metal	iron	7439-89-6	2.310	20.88	36.00	208769	359946	
wire	noble metal	gold	7440-57-5	0.017	0.15	0.15	1547	1547	
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9438		
	inorganic material	antimonytrioxide	1309-64-4	0.157	1.42		14157		
	plastics	brominated resin	-	0.196	1.77		17696		
	plastics	epoxy resin	-	1.632	14.75		147465		
	inorganic material	silicondioxide	60676-86-0	4.438	40.11	58.99	401104	589860	
leadfinish	non noble metal	tin	7440-31-5	0.219	1.98	1.98	19821	19821	
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27413	27413	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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